

This listing of claims will replace all prior versions, and listings, of claims in the application:

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Claims 1-21 (Cancelled).

B<sup>2</sup>  
22. (Currently Amended) A process for producing ~~the~~ a coated cemented carbide which comprises at least the steps of

(A) subjecting to at least surface-pretreatments of

(1) machining processing of at least part of a surface of a cemented carbide substrate comprising a hard phase containing tungsten carbide, and a binder phase, and

(2)(a) effecting an electro-chemical polishing treatment on the surface of the substrate or (2)(b) effecting the electro-chemical polishing treatment and a coating treatment onto at least part of the surface of the substrate with at least one of iron, cobalt and nickel an ~~iron-group metal element~~ and a compound thereof to form a uniform film, and then,

(B) providing at least one hard film, which comprises a single layer or two or more laminated layers, comprising at least one material selected from a carbide, a nitride and an oxide of an element selected from elements of the Groups 4, 5 and 6 of the Periodic Table, aluminum and silicon and a mutual solid solution thereof, on the surface of the resulting substrate.

23. (Original) The process according to Claim 22, wherein the machining processing is at least one selected from the group consisting of a whetstone grinding, brush grinding, lap processing, blast processing and ultrasonic wave processing.

24. (Currently Amended) The process according to Claim 22, wherein the electro-chemical polishing treatment ~~electropolishing processing~~ in the pretreatment is carried out by using an electrolytic solution containing, ~~as an essential component~~, at least one compound selected from the group consisting of a hydroxide, a nitrite, a sulfite, a phosphite or a ~~carbide~~ carbonate of a metal of Group 1 of the Periodic Table.

25. (Currently Amended) The process according to Claim 24, wherein the electrolytic solution comprises, ~~as an essential component~~, at least one compound selected from the group consisting of a nitrite of sodium and/or potassium, a hydroxide and a ferricyanide of the same, and a hydroxide and a chloride of the same.

B<sup>2</sup> 26. (Currently Amended) The process according to Claim 22, wherein the coating treatment in the pretreatment is at least one chemical coating method selected from the group consisting of electroplating, electroless plating, vacuum deposition, physical vapor deposition (PVD), chemical vapor deposition (CVD), colloid coating and solution coating; or at least one mechanical coating method selected from the group consisting of blast processing using a shot material mainly comprising an iron, cobalt and nickel ~~an iron-group metal~~ or a mixture of the shot material and at least one of a grinding material and a polishing material, and a shot processing.

27. (Currently Amended) The process according to Claim 26, wherein the coating treatment in the pretreatment is an electroplating using a solution containing iron, cobalt and nickel ~~an iron-group metal~~ as main component or a waste solution of the electrolytic solution in the ~~electropolishing~~ electro-chemical polishing treatment.

28. (New) The process according to Claim 22, wherein the process comprises the step (2)(a) of effecting the electro-chemical polishing treatment on the surface of the substrate.

29. (New) The process according to Claim 22, wherein the process comprises the step (2)(b) of effecting the electro-chemical polishing treatment and the coating treatment onto at least part of the surface of the substrate with at least one of iron, cobalt and nickel and a compound thereof to form the uniform film.

30. (New) The process according to claim 29, wherein the at least one of iron, cobalt and nickel comprises iron or a compound thereof.

31. (New) The process according to claim 29, wherein the at least one of iron, cobalt and nickel comprises cobalt or a compound thereof.

32. (New) The process according to claim 29, wherein the at least one of iron, cobalt and nickel comprises nickel or a compound thereof.

33. (New) The process according to claim 22, wherein the hard film comprises a TiN layer.

34. (New) The process according to claim 22, wherein the hard film comprises a TiCN layer.

35. (New) The process according to claim 22, wherein the hard film comprises an Al<sub>2</sub>O<sub>3</sub> layer.

36. (New) The process according to claim 22, wherein the hard film comprises a first TiN layer, a TiCN layer, an Al<sub>2</sub>O<sub>3</sub> layer and a second TiN layer.

37. (New) The process according to claim 22, wherein a deformed layer on the surface of the substrate is removed by the electro-chemical polishing treatment.